



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-07-27
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section		Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L5300AH7TR	A695*UN41AA6	A	3068	2020-07-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	290	mg	Each	ECOPACK 1
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	CD00263648	

Package Designator	Size	Nbr of instances	Shape	
SIP	6.50,6.10,2.30	6	gull wing	
Comment	TO-252 6 LEADS SMD (HPAK)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.01	die	48
Lead	1.24	soft solder	4272
Antimony trioxide	1.03	encapsulation	3552

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	1.24	Soft solder	4272
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	1.239	Soft solder	955281

Material Composition Declaration :						Mfr Item Name	A695*UN41AA6					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.826	mg	supplier	die	Silicon(Si)	7440-21-3		2.691	mg	952230	9280
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.018	mg	6369	62
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.002	mg	708	7
				supplier	metallisation	Gold(Au)	7440-57-5		0.004	mg	1415	14
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.014	mg	4954	48
				supplier	metallisation	Tungsten(W)	7440-33-7		0.028	mg	9908	97
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.004	mg	1415	14
				supplier	passivation	Silicon oxide	7631-86-9		0.044	mg	15570	152
				supplier	polymer coating	Polyimide	Proprietary		0.021	mg	7431	72
				supplier	alloy & coating	Copper(Cu)	7440-50-8		196.898	mg	997335	678959
Leadframe	M-004 Copper and its alloys	197.424	mg	supplier	alloy & coating	Iron(Fe)	7439-89-6		0.091	mg	461	314
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.166	mg	841	572
				supplier	alloy & coating	Silver (Ag)	7440-22-4		0.269	mg	1363	928
				supplier	alloy & coating	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	1.239	mg	955282	4272
Soft solder	Solder	1.297	mg	SVHC	solder	Silver(Ag)	7440-22-4		0.032	mg	24672	110
				supplier	solder	Tin(Sn)	7440-31-5		0.026	mg	20046	90
				supplier	solder	Silica vitreous	60676-86-0		70.613	mg	822995	243493
Encapsulation	M-011 Other inorganic materials	85.800	mg	supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		6.006	mg	70000	20710
				supplier	mold compound	Phenol resin	9003-35-4		3.432	mg	40000	11834
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		2.574	mg	30000	8876
				supplier	mold compound	Antimony trioxide	1309-64-4		1.030	mg	12005	3552
				supplier	mold compound	Brominated epoxy resin	40039-93-8		1.716	mg	20000	5917
				supplier	mold compound	Carbon black	1333-86-4		0.429	mg	5000	1479
				supplier	mold compound	Carbon black	1333-86-4		0.429	mg	5000	1479
connections coating	Solder	2.653	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.653	mg	1000000	9148